

Welcome to E-XFL.COM

#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

### Details

Details	
Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 9x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	40-WFQFN Exposed Pad
Supplier Device Package	40-HWQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f100ecgna-u0

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

### Table 1-1. List of Ordering Part Numbers

				(1/12)
Pin	Package	Data	Fields of	Ordering Part Number
count		flash	Application Note	
20 pins	20-pin plastic LSSOP	Mounted	А	R5F1006AASP#V0, R5F1006CASP#V0, R5F1006DASP#V0,
	(7.62 mm (300), 0.65			R5F1006EASP#V0
	mm pitch)			R5F1006AASP#X0, R5F1006CASP#X0, R5F1006DASP#X0,
				R5F1006EASP#X0
			D	R5F1006ADSP#V0, R5F1006CDSP#V0, R5F1006DDSP#V0,
				R5F1006EDSP#V0
				R5F1006ADSP#X0, R5F1006CDSP#X0, R5F1006DDSP#X0,
				R5F1006EDSP#X0
			G	R5F1006AGSP#V0, R5F1006CGSP#V0, R5F1006DGSP#V0,
				R5F1006EGSP#V0
				R5F1006AGSP#X0, R5F1006CGSP#X0, R5F1006DGSP#X0,
				R5F1006EGSP#X0
		Not	А	R5F1016AASP#V0, R5F1016CASP#V0, R5F1016DASP#V0,
		mounted		R5F1016EASP#V0
				R5F1016AASP#X0, R5F1016CASP#X0, R5F1016DASP#X0,
				R5F1016EASP#X0
			D	R5F1016ADSP#V0, R5F1016CDSP#V0, R5F1016DDSP#V0,
				R5F1016EDSP#V0
				R5F1016ADSP#X0, R5F1016CDSP#X0, R5F1016DDSP#X0,
				R5F1016EDSP#X0
24 pins	24-pin plastic	Mounted	А	R5F1007AANA#U0, R5F1007CANA#U0, R5F1007DANA#U0,
	HWQFN (4 $ imes$ 4mm,			R5F1007EANA#U0
	0.5 mm pitch)			R5F1007AANA#W0, R5F1007CANA#W0, R5F1007DANA#W0,
				R5F1007EANA#W0
			D	R5F1007ADNA#U0, R5F1007CDNA#U0, R5F1007DDNA#U0,
				R5F1007EDNA#U0
				R5F1007ADNA#W0, R5F1007CDNA#W0, R5F1007DDNA#W0,
				R5F1007EDNA#W0
			G	R5F1007AGNA#U0, R5F1007CGNA#U0, R5F1007DGNA#U0,
				R5F1007EGNA#U0
				R5F1007AGNA#W0, R5F1007CGNA#W0, R5F1007DGNA#W0,
				R5F1007EGNA#W0
		Not	А	R5F1017AANA#U0, R5F1017CANA#U0, R5F1017DANA#U0,
		mounted		R5F1017EANA#U0
				R5F1017AANA#W0, R5F1017CANA#W0, R5F1017DANA#W0,
				R5F1017EANA#W0
			D	R5F1017ADNA#U0, R5F1017CDNA#U0, R5F1017DDNA#U0,
				R5F1017EDNA#U0
				R5F1017ADNA#W0, R5F1017CDNA#W0, R5F1017DDNA#W0,
				R5F1017EDNA#W0

Note For the fields of application, refer to Figure 1-1 Part Number, Memory Size, and Package of RL78/G13.

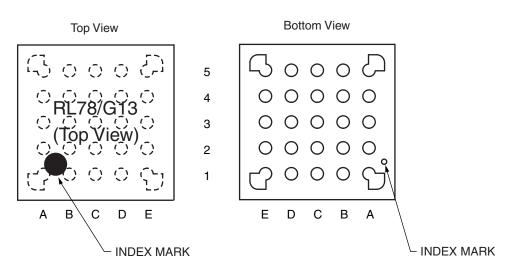
Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.



### 1.3.3 25-pin products

• 25-pin plastic WFLGA (3 × 3 mm, 0.50 mm pitch)





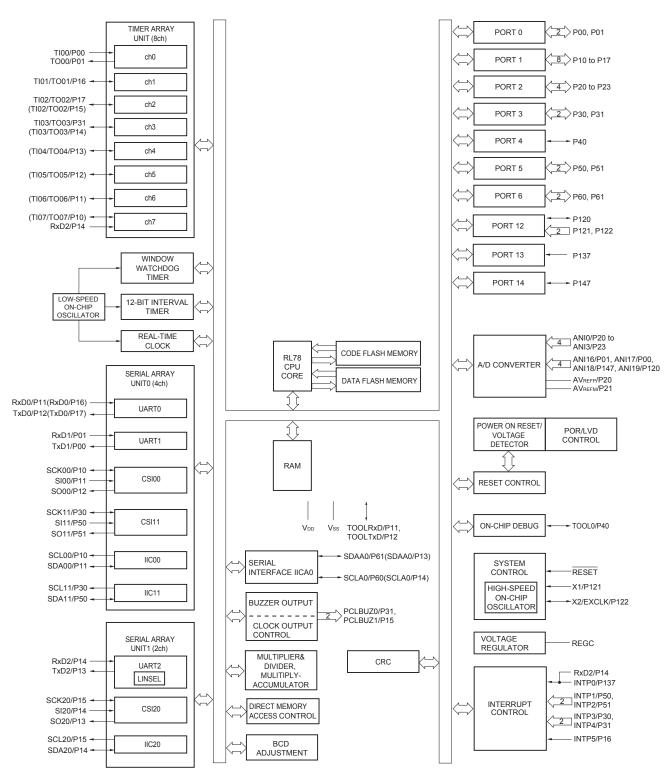
	А	В	С	D	E	_
5	P40/TOOL0	RESET	P01/ANI16/ TO00/RxD1	P22/ANI2	P147/ANI18	5
4	P122/X2/ EXCLK	P137/INTP0	P00/ANI17/ TI00/TxD1	P21/ANI1/ AVrefm	P10/SCK00/ SCL00	4
3	P121/X1	Vdd	P20/ANI0/ AV <sub>REFP</sub>	P12/SO00/ TxD0/ TOOLTxD	P11/SI00/ RxD0/ TOOLRxD/ SDA00	3
2	REGC	Vss	P30/INTP3/ SCK11/SCL11	P17/Tl02/ TO02/SO11	P50/INTP1/ SI11/SDA11	2
1	P60/SCLA0	P61/SDAA0	P31/TI03/ TO03/INTP4/ PCLBUZ0	P16/TI01/ TO01/INTP5	P130	1
	А	В	С	D	E	

### Caution Connect the REGC pin to Vss via a capacitor (0.47 to 1 $\mu$ F).

**Remark** For pin identification, see **1.4 Pin Identification**.



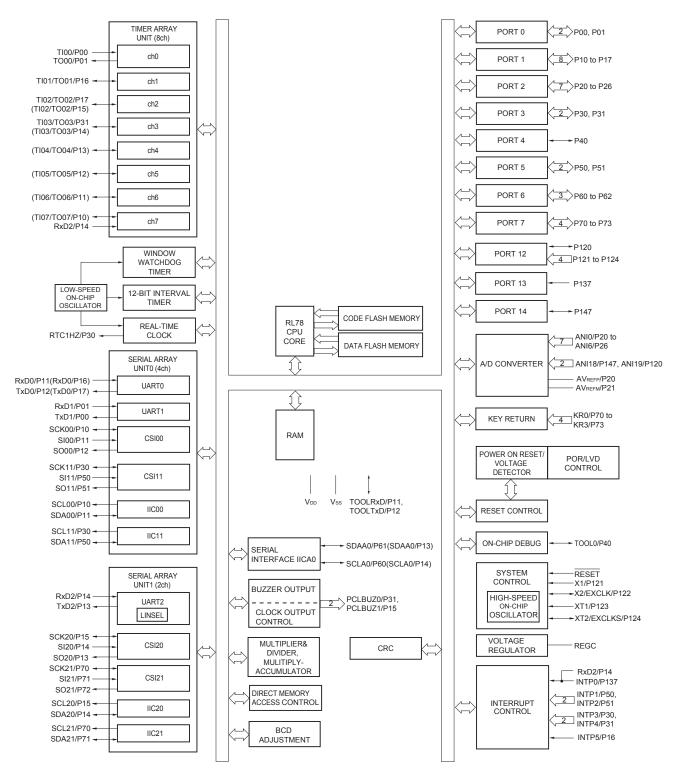
### 1.5.4 30-pin products



**Remark** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR) in the RL78/G13 User's Manual.



### 1.5.7 40-pin products



**Remark** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR) in the RL78/G13 User's Manual.



## 2.1 Absolute Maximum Ratings

Absolute Maximum Ratings ( $T_A = 25^{\circ}C$ ) (	(1/2)	
--	-------	--

Parameter	Symbols	Conditions	Ratings	Unit
Supply voltage	VDD		–0.5 to +6.5	V
	EVDD0, EVDD1	EVDD0 = EVDD1	–0.5 to +6.5	V
	EVsso, EVss1	EVsso = EVss1	–0.5 to +0.3	V
REGC pin input voltage	VIREGC	REGC	-0.3 to +2.8 and -0.3 to V <sub>DD</sub> +0.3 <sup>Note 1</sup>	V
Input voltage	VI1	P00 to P07, P10 to P17, P30 to P37, P40 to P47,	-0.3 to EVDD0 +0.3	V
		P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	and –0.3 to V <sub>DD</sub> +0.3 <sup>Note 2</sup>	
	VI2	P60 to P63 (N-ch open-drain)	–0.3 to +6.5	V
	Vı3	P20 to P27, P121 to P124, P137, P150 to P156, EXCLK, EXCLKS, RESET	-0.3 to V <sub>DD</sub> +0.3 <sup>Note 2</sup>	V
Output voltage	Voi	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147		V
	V <sub>02</sub>	P20 to P27, P150 to P156	-0.3 to VDD +0.3 Note 2	V
Analog input voltage	VAI1	ANI16 to ANI26	-0.3 to EV <sub>DD0</sub> +0.3 and $-0.3$ to AV <sub>REF</sub> (+) +0.3 <sup>Notes 2, 3</sup>	V
	Vai2	ANI0 to ANI14	$-0.3$ to V_DD +0.3 and $-0.3$ to AV_REF(+) +0.3 $^{Notes2,3}$	V

- **Notes 1.** Connect the REGC pin to Vss via a capacitor (0.47 to 1  $\mu$ F). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.
  - 2. Must be 6.5 V or lower.
  - 3. Do not exceed AVREF(+) + 0.3 V in case of A/D conversion target pin.
- Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.
- **Remarks 1.** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.
  - **2.**  $AV_{REF}(+)$ : + side reference voltage of the A/D converter.
  - 3. Vss : Reference voltage



## (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products

# $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le \text{EV}_{\text{DD}0} = \text{EV}_{\text{DD}1} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, \text{Vss} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0 \text{ V})$ (1/2)

Parameter	Symbol			Conditions			MIN.	TYP.	MAX.	Unit
Supply	IDD1	Operating	HS (high-	$f_{IH} = 32 \text{ MHz}^{Note 3}$	Basic	$V_{DD} = 5.0 V$		2.3		mA
Current		mode	speed main) mode <sup>Note 5</sup>		operation	$V_{\text{DD}} = 3.0 \text{ V}$		2.3		mA
			mode		Normal	V <sub>DD</sub> = 5.0 V		5.2	8.5	mA
					operation	V <sub>DD</sub> = 3.0 V		5.2	8.5	mA
				$f_{IH} = 24 \text{ MHz}^{Note 3}$	Normal	V <sub>DD</sub> = 5.0 V		4.1	6.6	mA
					operation	V <sub>DD</sub> = 3.0 V		4.1	6.6	mA
				fin = 16 MHz <sup>Note 3</sup>	Normal	V <sub>DD</sub> = 5.0 V		3.0	4.7	mA
					operation	V <sub>DD</sub> = 3.0 V		3.0	4.7	mA
			LS (low-	f <sub>IH</sub> = 8 MHz <sup>№te 3</sup>	Normal	V <sub>DD</sub> = 3.0 V		1.3	2.1	mA
			speed main) mode <sup>Note 5</sup>		operation	V <sub>DD</sub> = 2.0 V		1.3	2.1	mA
			LV (low-	$f_{IH} = 4 \ MHz^{Note \ 3}$	Normal	$V_{DD} = 3.0 V$		1.3	1.8	mA
			voltage main) mode		operation	V <sub>DD</sub> = 2.0 V		1.3	1.8	mA
			HS (high- speed main) mode <sup>Note 5</sup>	f <sub>MX</sub> = 20 MHz <sup>Note 2</sup> ,	Normal	Square wave input		3.4	5.5	mA
				V <sub>DD</sub> = 5.0 V	operation	Resonator connection		3.6	5.7	mA
				$f_{MX} = 20 \text{ MHz}^{Note 2},$	Normal	Square wave input		3.4	5.5	mA
				$V_{DD} = 3.0 V$	operation	Resonator connection		3.6	5.7	mA
				$f_{MX} = 10 \text{ MHz}^{Note 2},$	Normal operation Normal	Square wave input		2.1	3.2	mA
				$V_{DD} = 5.0 V$		Resonator connection		2.1	3.2	mA
				$f_{MX} = 10 \text{ MHz}^{Note 2},$		Square wave input		2.1	3.2	mA
				$V_{DD} = 3.0 V$	operation	Resonator connection		2.1	3.2	mA
			LS (low- speed main) mode Note 5	$f_{MX} = 8 \text{ MHz}^{Note 2},$	Normal	Square wave input		1.2	2.0	mA
				$V_{DD} = 3.0 V$	operation	Resonator connection		1.2	2.0	mA
				$f_{MX} = 8 \text{ MHz}^{Note 2},$	Normal	Square wave input		1.2	2.0	mA
				V <sub>DD</sub> = 2.0 V	operation	Resonator connection		1.2	2.0	mA
			Subsystem	fsuв = 32.768 kHz	Normal	Square wave input		4.8	5.9	μA
			clock operation	Note 4 $T_A = -40^{\circ}C$	operation	Resonator connection		4.9	6.0	μA
				fsuв = 32.768 kHz	Normal	Square wave input		4.9	5.9	μA
				Note 4 $T_A = +25^{\circ}C$	operation	Resonator connection		5.0	6.0	μA
				fsuв = 32.768 kHz	Normal	Square wave input		5.0	7.6	μA
				Note 4	operation	Resonator connection		5.1	7.7	μA
				T <sub>A</sub> = +50°C fsub = 32.768 kHz	Normal	Square wave input		5.2	9.3	μA
				Note 4	operation	Resonator connection		5.3	9.3 9.4	μA
				$T_A = +70^{\circ}C$	Nama	Company to the state of		F 7	10.0	
				fsub = 32.768 kHz Note 4	Normal operation	Square wave input Resonator connection		5.7 5.8	13.3 13.4	μA μA
				T <sub>A</sub> = +85°C	.	TESUTIALUI CUTITIECUUT		5.0	13.4	μΑ

(Notes and Remarks are listed on the next page.)



- **Notes 1.** Total current flowing into Vbb, EVbbb, and EVbb1, including the input leakage current flowing when the level of the input pin is fixed to Vbb, EVbb0, and EVbb1, or Vss, EVsso, and EVss1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. During HALT instruction execution by flash memory.
  - 3. When high-speed on-chip oscillator and subsystem clock are stopped.
  - 4. When high-speed system clock and subsystem clock are stopped.
  - 5. When high-speed on-chip oscillator and high-speed system clock are stopped. When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1). The current flowing into the RTC is included. However, not including the current flowing into the 12-bit interval timer and watchdog timer.
  - 6. Not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
  - 7. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
    - HS (high-speed main) mode: 2.7 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 32 MHz
      - 2.4 V  $\leq$  V\_{DD}  $\leq$  5.5 V@1 MHz to 16 MHz
    - LS (low-speed main) mode: ~~ 1.8 V  $\leq$  V\_{DD}  $\leq$  5.5 V@1 MHz to 8 MHz
    - LV (low-voltage main) mode: 1.6 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 4 MHz
  - 8. Regarding the value for current to operate the subsystem clock in STOP mode, refer to that in HALT mode.
- **Remarks 1.** f<sub>MX</sub>: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: High-speed on-chip oscillator clock frequency
  - 3. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
  - 4. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is  $T_A = 25^{\circ}C$



- **Notes 1.** Total current flowing into VDD, EVDDO, and EVDD1, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDDO, and EVDD1, or Vss, EVSSO, and EVSS1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. When high-speed on-chip oscillator and subsystem clock are stopped.
  - 3. When high-speed system clock and subsystem clock are stopped.
  - 4. When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
  - **5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
    - HS (high-speed main) mode:  $2.7 \text{ V} \le \text{V}_{\text{DD}} \le 5.5 \text{ V} @ 1 \text{ MHz}$  to 32 MHz
      - 2.4 V  $\leq$  V<sub>DD</sub>  $\leq$  5.5 V@1 MHz to 16 MHz
    - LS (low-speed main) mode:  $~~1.8~V \leq V_{\text{DD}} \leq 5.5~V~$  @1 MHz to 8 MHz
    - LV (low-voltage main) mode: 1.6 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 4 MHz
- Remarks 1. fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: High-speed on-chip oscillator clock frequency
  - **3.** fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
  - 4. Except subsystem clock operation, temperature condition of the TYP. value is  $T_A = 25^{\circ}C$



# **AC Timing Test Points** Vін/Vон Vін/Vон Test points VIL/VOL VIL/VOL **External System Clock Timing** 1/f<sub>EX</sub>/ 1/f<sub>EXS</sub> texl/ texн/ **t**EXLS **t**EXHS EXCLK/EXCLKS **TI/TO Timing** t⊤ı∟ tтıн TI00 to TI07, TI10 to TI17 **1/f**то TO00 to TO07, TO10 to TO17 **Interrupt Request Input Timing** tINTL **t**INTH INTP0 to INTP11 **Key Interrupt Input Timing t**ĸĸ KR0 to KR7 **RESET** Input Timing tRSL RESET



			$\sqrt{DD0} = EVDD1 \le VDD \le$						1.177	1	Lint
Parameter	Symbol		Conditions			high-		low-		low-	Unit
						main) ode	speed	main) ode		age Mode	
								1			
					MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate		Transmission	$4.0 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V},$			Note		Note		Note	bps
			$2.7 \text{ V} \leq V_b \leq 4.0 \text{ V}$			1		1		1	
				Theoretical		2.8		2.8		2.8	Mbps
				value of the		Note 2		Note 2		Note 2	
				maximum							
				transfer rate							
				C <sub>b</sub> = 50 pF, R <sub>b</sub> =							
				$1.4 \text{ k}\Omega, V_{\text{b}} = 2.7$							
				V							
			$2.7 \text{ V} \le \text{EV}_{\text{DD0}} < 4.0 \text{ V},$			Note		Note		Note	bps
			$2.3~V \leq V_b \leq 2.7~V$			3		3		3	
				Theoretical		1.2		1.2		1.2	Mbps
				value of the		Note 4		Note 4		Note 4	
				maximum							
				transfer rate							
				$C_b = 50 \text{ pF}, R_b =$							
				$2.7 \text{ k}\Omega$ , V <sub>b</sub> = $2.3$							
				V							
			$1.8 \text{ V} \leq \text{EV}_{\text{DD0}} < 3.3 \text{ V},$			Notes		Notes		Notes	bps
			$1.6~V \leq V_b \leq 2.0~V$			5, 6		5, 6		5, 6	
				Theoretical		0.43		0.43		0.43	Mbps
				value of the		Note 7		Note 7		Note 7	
				maximum							
				transfer rate							
				$C_b = 50 \text{ pF}, R_b =$							
				$5.5 \text{ k}\Omega, \text{V}_{\text{b}} = 1.6$							
				V							

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (2/2) (TA = -40 to +85°C, 1.8 V  $\leq$  EVDD0 = EVDD1  $\leq$  VDD  $\leq$  5.5 V, Vss = EVss0 = EVss1 = 0 V)

**Notes 1.** The smaller maximum transfer rate derived by using fMck/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V  $\leq$  EV  $_{DD0} \leq$  5.5 V and 2.7 V  $\leq$  V  $_{b} \leq$  4.0 V

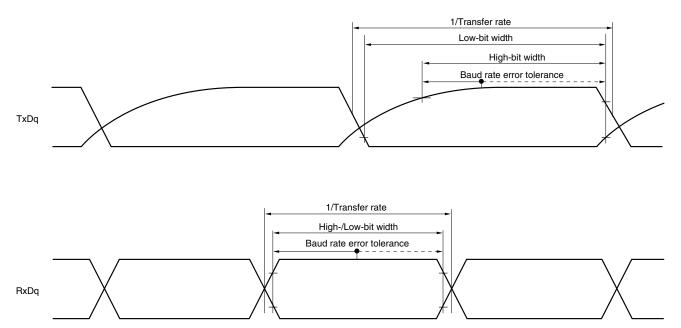
Maximum transfer rate = 
$$\frac{1}{\{-C_b \times R_b \times \ln (1 - \frac{2.2}{V_b})\} \times 3}$$
 [bps]

Baud rate error (theoretical value) = 
$$\frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 [\%]$$

- \* This value is the theoretical value of the relative difference between the transmission and reception sides.
- This value as an example is calculated when the conditions described in the "Conditions" column are met. Refer to Note 1 above to calculate the maximum transfer rate under conditions of the customer.







- **2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
- **3.** fMCK: Serial array unit operation clock frequency
  (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).
  m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))
- **4.** UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.



## 2.8 Flash Memory Programming Characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
CPU/peripheral hardware clock frequency	fclк	$1.8~V \leq V_{DD} \leq 5.5~V$	1		32	MHz
Number of code flash rewrites Notes 1, 2, 3	Cerwr	Retained for 20 years TA = 85°C	1,000			Times
Number of data flash rewrites Notes 1, 2, 3		Retained for 1 years Ta = 25°C		1,000,000		
		Retained for 5 years TA = 85°C	100,000			
		Retained for 20 years TA = 85°C	10,000			

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V}, \text{ V}_{SS} = 0 \text{ V})$ 

**Notes 1.** 1 erase + 1 write after the erase is regarded as 1 rewrite.

The retaining years are until next rewrite after the rewrite.

- 2. When using flash memory programmer and Renesas Electronics self programming library
- **3.** These are the characteristics of the flash memory and the results obtained from reliability testing by Renesas Electronics Corporation.

### 2.9 Dedicated Flash Memory Programmer Communication (UART)

### $(T_{\text{A}} = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \leq \text{EV}_{\text{DD}} = \text{EV}_{\text{DD}} \leq 5.5 \text{ V}, \text{Vss} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate		During serial programming	115,200		1,000,000	bps



- **Notes 1.** Total current flowing into V<sub>DD</sub> and EV<sub>DD0</sub>, including the input leakage current flowing when the level of the input pin is fixed to V<sub>DD</sub>, EV<sub>DD0</sub> or Vss, EV<sub>SS0</sub>. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. When high-speed on-chip oscillator and subsystem clock are stopped.
  - 3. When high-speed system clock and subsystem clock are stopped.
  - 4. When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
  - 5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 32 MHz

2.4 V 
$$\leq$$
 V<sub>DD</sub>  $\leq$  5.5 V@1 MHz to 16 MHz

- **Remarks 1.** f<sub>MX</sub>: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: High-speed on-chip oscillator clock frequency
  - 3. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
  - 4. Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C



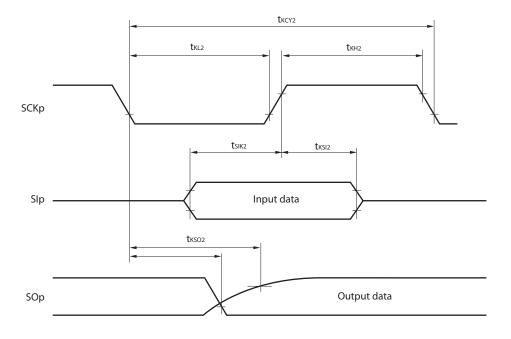
- **Notes 1.** Total current flowing into VDD, EVDDD, and EVDD1, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDDD, and EVDD1, or Vss, EVsso, and EVss1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. When high-speed on-chip oscillator and subsystem clock are stopped.
  - 3. When high-speed system clock and subsystem clock are stopped.
  - **4.** When high-speed on-chip oscillator and high-speed system clock are stopped. When AMPHS1 = 1 (Ultra-low power consumption oscillation). However, not including the current flowing into the 12-bit interval timer and watchdog timer.
  - **5.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V  $\leq$  V\_DD  $\leq$  5.5 V@1 MHz to 32 MHz

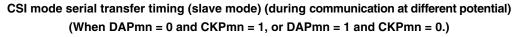
2.4 V  $\leq$  V<sub>DD</sub>  $\leq$  5.5 V@1 MHz to 16 MHz

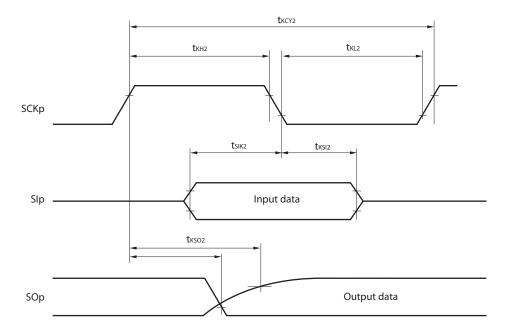
- **Remarks 1.** fMX: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: High-speed on-chip oscillator clock frequency
  - 3. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
  - 4. Except subsystem clock operation, temperature condition of the TYP. value is  $T_A = 25^{\circ}C$





CSI mode serial transfer timing (slave mode) (during communication at different potential) (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)





**Remarks 1.** p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number,

n: Channel number (mn = 00, 01, 02, 10, 12. 13), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)

**2.** CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

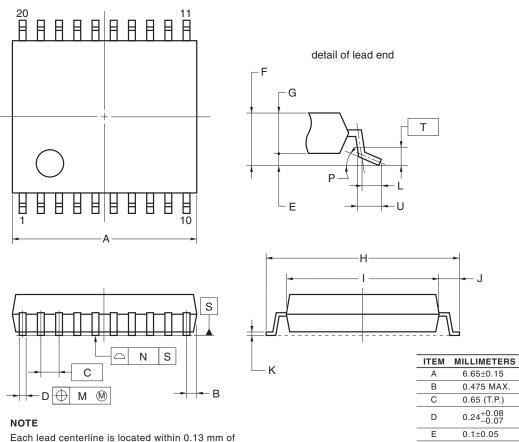


# 4. PACKAGE DRAWINGS

### 4.1 20-pin Products

R5F1006AASP, R5F1006CASP, R5F1006DASP, R5F1006EASP R5F1016AASP, R5F1016CASP, R5F1016DASP, R5F1016EASP R5F1006ADSP, R5F1006CDSP, R5F1006DDSP, R5F1006EDSP R5F1016ADSP, R5F1016CDSP, R5F1016DDSP, R5F1016EDSP R5F1006AGSP, R5F1006CGSP, R5F1006DGSP, R5F1006EGSP

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LSSOP20-0300-0.65	PLSP0020JC-A	S20MC-65-5A4-3	0.12



Each lead centerline is located within 0.13 mm of its true position (T.P.) at maximum material condition.

	( )
D	$0.24^{+0.08}_{-0.07}$
E	0.1±0.05
F	1.3±0.1
G	1.2
Н	8.1±0.2
I	6.1±0.2
J	1.0±0.2
К	0.17±0.03
L	0.5
Μ	0.13
Ν	0.10
Р	$3^{\circ}^{+5}_{-3^{\circ}}^{\circ}$
Т	0.25
U	0.6±0.15

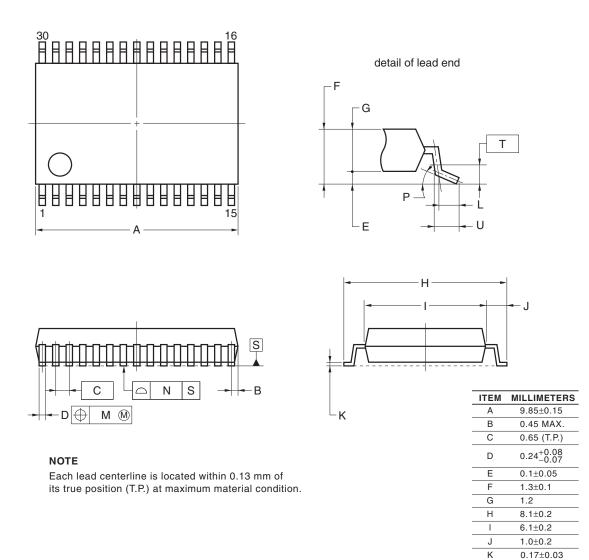
© 2012 Renesas Electronics Corporation. All rights reserved.



### 4.4 30-pin Products

R5F100AAASP, R5F100ACASP, R5F100ADASP, R5F100AEASP, R5F100AFASP, R5F100AGASP R5F101AAASP, R5F101ACASP, R5F101ADASP, R5F101AEASP, R5F101AFASP, R5F101AGASP R5F100AADSP, R5F100ACDSP, R5F100ADDSP, R5F100AEDSP, R5F100AFDSP, R5F100AGDSP R5F101AADSP, R5F101ACDSP, R5F101ADDSP, R5F101AEDSP, R5F101AFDSP, R5F101AGDSP R5F100AAGSP, R5F100ACGSP, R5F100ADGSP, R5F100AEGSP, R5F100AFGSP, R5F100AGGSP

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LSSOP30-0300-0.65	PLSP0030JB-B	S30MC-65-5A4-3	0.18





0.5

0.13

0.10 3°+5°

0.25

0.6±0.15

L

M N

P T

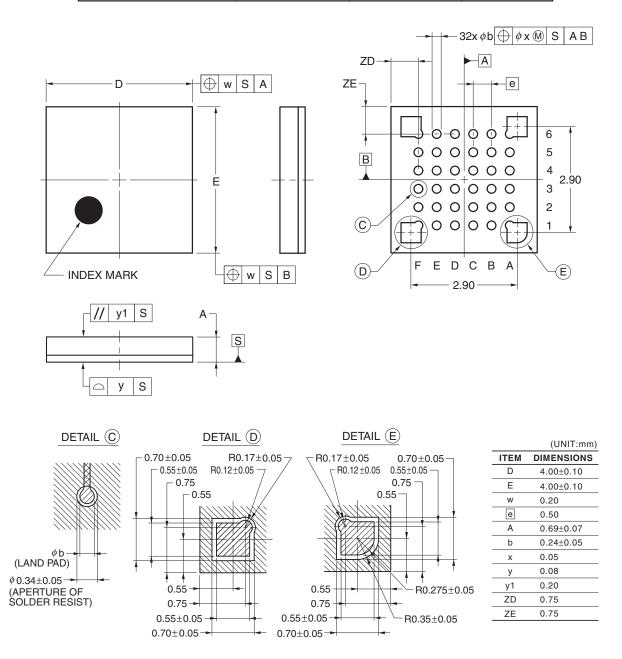
U

©2012 Renesas Electronics Corporation. All rights reserved.

### 4.6 36-pin Products

R5F100CAALA, R5F100CCALA, R5F100CDALA, R5F100CEALA, R5F100CFALA, R5F100CGALA R5F101CAALA, R5F101CCALA, R5F101CDALA, R5F101CEALA, R5F101CFALA, R5F101CGALA R5F100CAGLA, R5F100CCGLA, R5F100CDGLA, R5F100CEGLA, R5F100CFGLA, R5F100CGGLA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA36-4x4-0.50	PWLG0036KA-A	P36FC-50-AA4-2	0.023



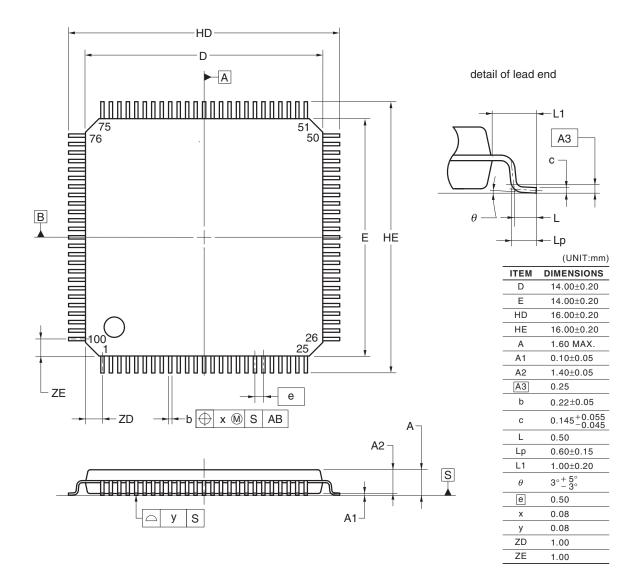
©2012 Renesas Electronics Corporation. All rights reserved.



### 4.13 100-pin Products

R5F100PFAFB, R5F100PGAFB, R5F100PHAFB, R5F100PJAFB, R5F100PKAFB, R5F100PLAFB R5F101PFAFB, R5F101PGAFB, R5F101PHAFB, R5F101PJAFB, R5F101PKAFB, R5F101PLAFB R5F100PFDFB, R5F100PGDFB, R5F100PHDFB, R5F100PJDFB, R5F100PKDFB, R5F100PLDFB R5F101PFDFB, R5F101PGDFB, R5F101PHDFB, R5F101PJDFB, R5F101PKDFB, R5F101PLDFB R5F100PFGFB, R5F100PGGFB, R5F100PHGFB, R5F100PJGFB

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LFQFP100-14x14-0.50	PLQP0100KE-A	P100GC-50-GBR-1	0.69



©2012 Renesas Electronics Corporation. All rights reserved.



Rev.	Date	Description		
		Page	Summary	
3.00	Aug 02, 2013	163	Modification of table in (8) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified $I^2C$ mode) (1/2)	
		164, 165	Modification of table, note 1, and caution in (8) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified I <sup>2</sup> C mode) (2/2)	
		166	Modification of table in 3.5.2 Serial interface IICA	
		166	Modification of IICA serial transfer timing	
		167	Addition of table in 3.6.1 A/D converter characteristics	
		167, 168	Modification of table and notes 3 and 4 in 3.6.1 (1)	
		169	Modification of description in 3.6.1 (2)	
		170	Modification of description and note 3 in 3.6.1 (3)	
		171	Modification of description and notes 3 and 4 in 3.6.1 (4)	
		172	Modification of table and note in 3.6.3 POR circuit characteristics	
		173	Modification of table of LVD Detection Voltage of Interrupt & Reset Mode	
		173	Modification from Supply Voltage Rise Time to 3.6.5 Power supply voltage rising slope characteristics	
		174	Modification of 3.9 Dedicated Flash Memory Programmer Communication (UART)	
		175	Modification of table, figure, and remark in 3.10 Timing Specs for Switching Flash Memory Programming Modes	
3.10	Nov 15, 2013	123	Caution 4 added.	
		125	Note for operating ambient temperature in 3.1 Absolute Maximum Ratings deleted.	
3.30	Mar 31, 2016		Modification of the position of the index mark in 25-pin plastic WFLGA ( $3 \times 3$ mm, 0.50 mm pitch) of 1.3.3 25-pin products	
			Modification of power supply voltage in 1.6 Outline of Functions [20-pin, 24- pin, 25-pin, 30-pin, 32-pin, 36-pin products]	
			Modification of power supply voltage in 1.6 Outline of Functions [40-pin, 44- pin, 48-pin, 52-pin, 64-pin products]	
			Modification of power supply voltage in 1.6 Outline of Functions [80-pin, 100- pin, 128-pin products]	
			ACK corrected to ACK	
			ACK corrected to ACK	

All trademarks and registered trademarks are the property of their respective owners.

SuperFlash is a registered trademark of Silicon Storage Technology, Inc. in several countries including the United States and Japan.

Caution: This product uses SuperFlash<sup>®</sup> technology licensed from Silicon Storage Technology, Inc.